

N-Channel Enhancement Mode MOSFET

TDM3482

DESCRIPTION

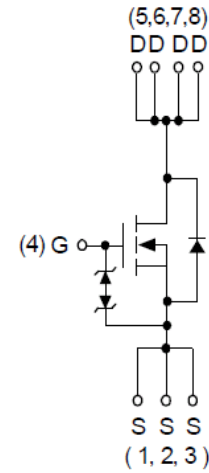
The TDM3482 uses advanced trench technology to provide excellent $R_{DS(ON)}$ and low gate charge. This device is suitable for use as a load switch or in PWM applications.

GENERAL FEATURES

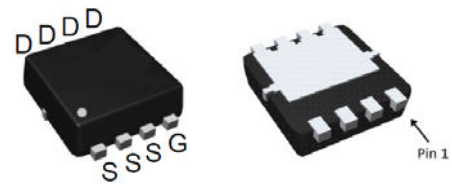
- $R_{DS(ON)} < 16m\Omega$ @ $V_{GS}=4.5V$
 $R_{DS(ON)} < 9.5m\Omega$ @ $V_{GS}=10V$
- High Power and current handling capability
- ESD protection
- Lead free product is available
- Surface Mount Package

Application

- PWM applications
- Load switch
- Power management



N-Channel MOSFET



PPAK-3*3-8

ABSOLUTE MAXIMUM RATINGS ($T_A=25^\circ C$ unless otherwise noted)

Parameter	Symbol	Limit	Unit
Drain-Source Voltage	V_{DS}	40	V
Gate-Source Voltage	V_{GS}	± 20	V
Diode Continuous Forward Current	I_S	10	A
Drain Current @ Continuous	I_D ($T_C=25^\circ C$)	43	A
	I_D ($T_C=100^\circ C$)	28	A
Drain Current @ Current-Pulsed (Note 1)	I_{DM} ($T_C=25^\circ C$)	60	A
Maximum Power Dissipation	P_D ($T_C=25^\circ C$)	27.8	W
	P_D ($T_C=100^\circ C$)	11.1	W
Drain Current @ Continuous	I_D ($T_A=25^\circ C$)	12	A
	I_D ($T_A=70^\circ C$)	9.6	A
Maximum Power Dissipation	P_D ($T_A=25^\circ C$)	2.08	W
	P_D ($T_A=70^\circ C$)	1.3	W
Maximum Operating Junction Temperature	T_J	150	$^\circ C$
Storage Temperature Range	T_{STG}	-55 To 150	$^\circ C$

N-Channel Enhancement Mode MOSFET
TDM3482
THERMAL CHARACTERISTICS

Thermal Resistance, Junction-to-Ambient (Note 4)	$R_{\theta JA}$ ($t \leq 10s$)	40	$^{\circ}C/W$
	$R_{\theta JA}$ (Steady State)	60	$^{\circ}C/W$
Thermal Resistance-Junction to Case	$R_{\theta JC}$ (Steady State)	4.5	$^{\circ}C/W$

ELECTRICAL CHARACTERISTICS ($T_A=25^{\circ}C$ unless otherwise noted)

Parameter	Symbol	Condition	Min	Typ	Max	Unit
OFF CHARACTERISTICS						
Drain-Source Breakdown Voltage	BV_{DSS}	$V_{GS}=0V, I_D=250\mu A$	40	-	-	V
Zero Gate Voltage Drain Current	I_{DSS}	$V_{DS}=32V, V_{GS}=0V$	-	-	1	μA
Gate-Body Leakage Current	I_{GSS}	$V_{GS}=\pm 20V, V_{DS}=0V$	-	-	± 10	μA
ON CHARACTERISTICS (Note 2)						
Gate Threshold Voltage	$V_{GS(th)}$	$V_{DS}=V_{GS}, I_D=250\mu A$	1.4	1.7	2.5	V
Drain-Source On-State Resistance	$R_{DS(on)}$	$V_{GS}=4.5V, I_D=8A$	-	11.5	16	$m\Omega$
		$V_{GS}=10V, I_D=15A$	-	7.9	9.5	$m\Omega$
		$T_J=125^{\circ}C$	-	11.8	-	$m\Omega$
DYNAMIC CHARACTERISTICS (Note 3)						
Gate Resistance	R_G	$V_{DS}=20V, V_{GS}=0V, F=1.0MHz$	-	1.7	-	Ω
Input Capacitance	C_{iss}	$V_{DS}=20V, V_{GS}=0V, F=1.0MHz$	-	700	-	PF
Output Capacitance	C_{oss}		-	191	-	PF
Reverse Transfer Capacitance	C_{rss}		-	30	-	PF
SWITCHING CHARACTERISTICS (Note 3)						
Turn-on Delay Time	$t_{d(on)}$	$V_{DS}=20V, R_L=20\Omega, V_{GEN}=10V, R_G=6\Omega, I_D=1A$	-	10	-	nS
Turn-on Rise Time	t_r		-	6.6	-	nS
Turn-Off Delay Time	$t_{d(off)}$		-	18	-	nS
Turn-Off Fall Time	t_f		-	12	-	nS
Total Gate Charge	Q_g	$V_{DS}=20V, I_D=15A, V_{GS}=4.5V$	-	5.1	-	nC
Gate-Source Charge	Q_{gs}		-	2.9	-	nC
Gate-Drain Charge	Q_{gd}		-	1.1	-	nC
Body Diode Reverse Recovery Time	T_{rr}	$I_F=5A, di/dt=100A/\mu s$	-	18.8	-	nS
Body Diode Reverse Recovery Charge	Q_{rr}		-	4.5	-	nC
DRAIN-SOURCE DIODE CHARACTERISTICS						
Diode Forward Voltage (Note 2)	V_{SD}	$V_{GS}=0V, I_S=20A$	-	0.8	1.1	V

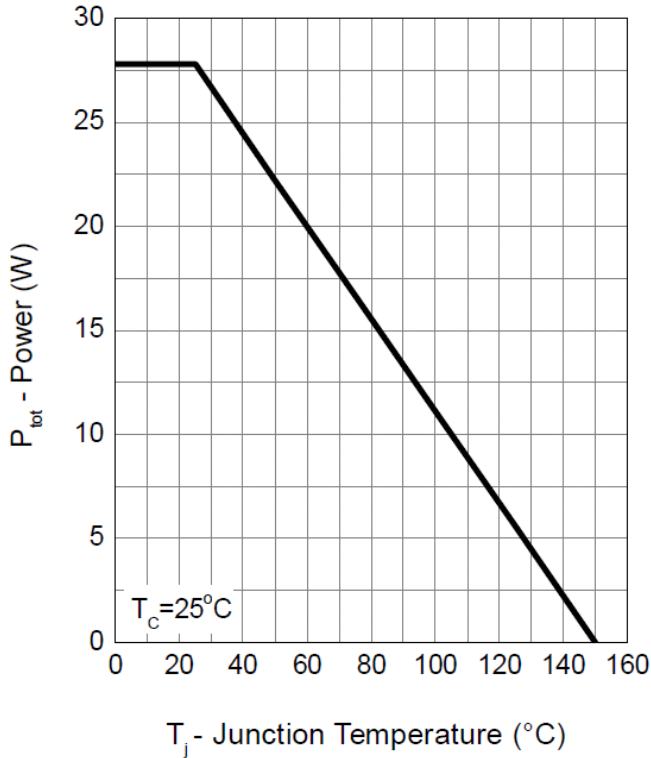
NOTES:

1. Pulse width limited by max. junction temperature.
2. Pulse Test: Pulse Width $\leq 300\mu s$, Duty Cycle $\leq 2\%$.
3. Guaranteed by design, not subject to production testing
4. $R_{\theta JA}$ steady state $t=100s$. $R_{\theta JA}$ is measured with the device mounted on 1in2, FR-4 board with 2oz. Copper.

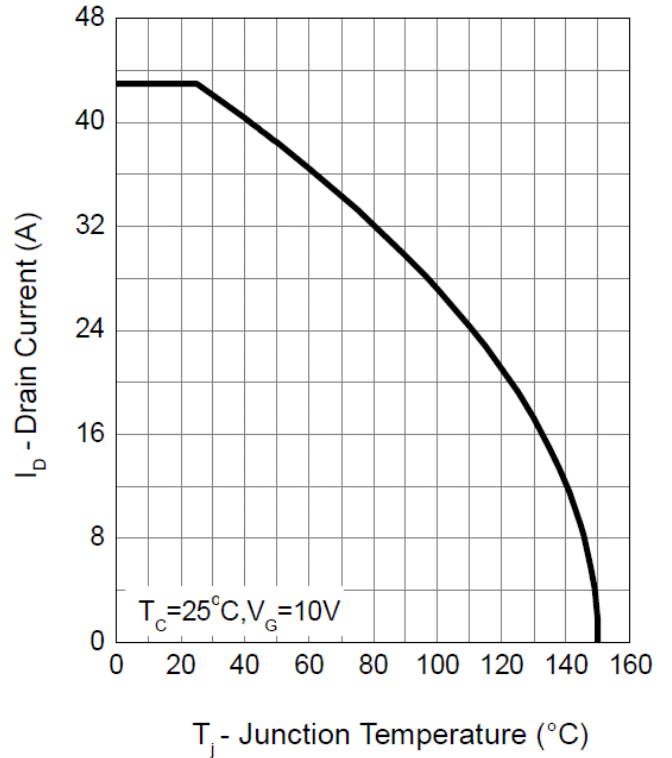
N-Channel Enhancement Mode MOSFET TDM3482

Typical Operating Characteristics

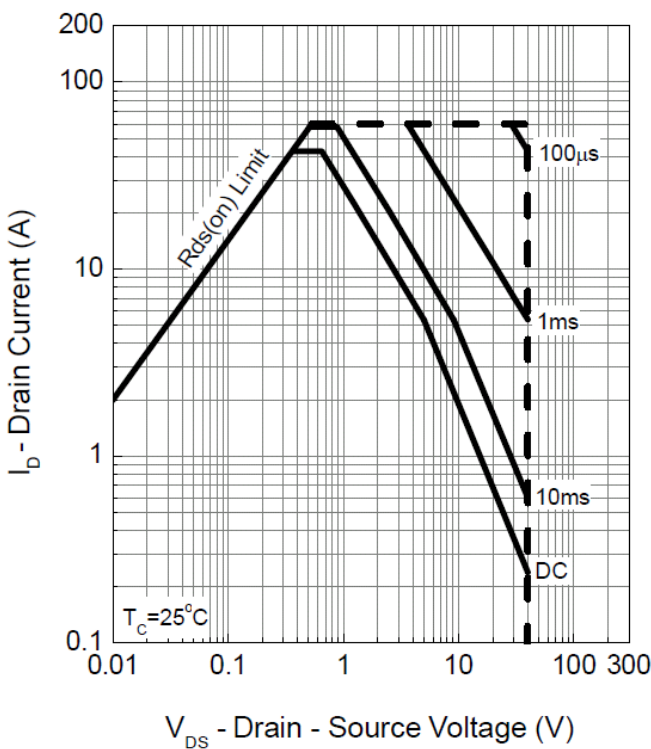
Power Dissipation



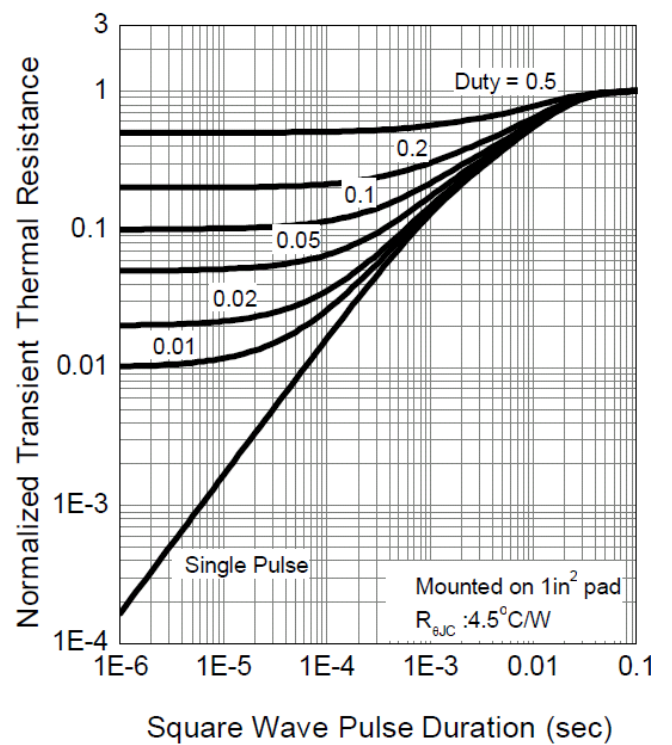
Drain Current



Safe Operation Area

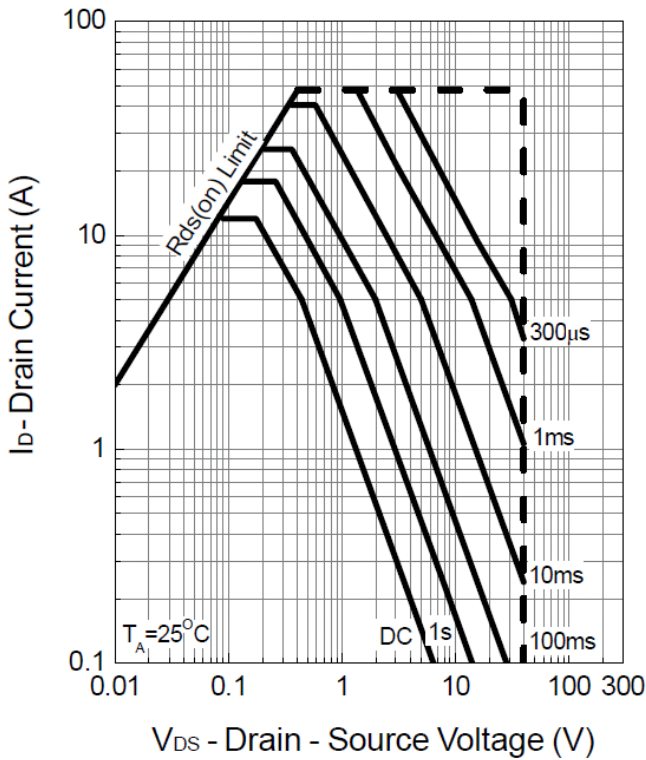


Thermal Transient Impedance

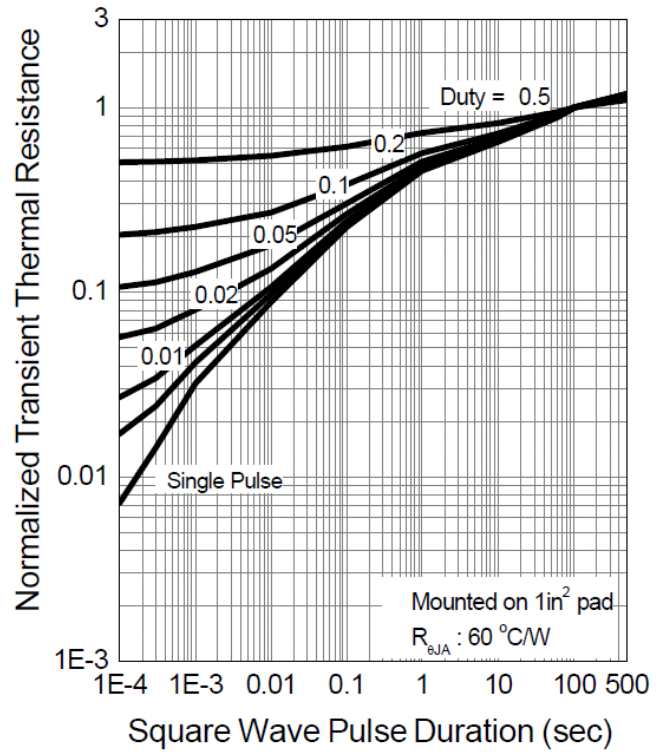


Typical Operating Characteristics(Cont.)

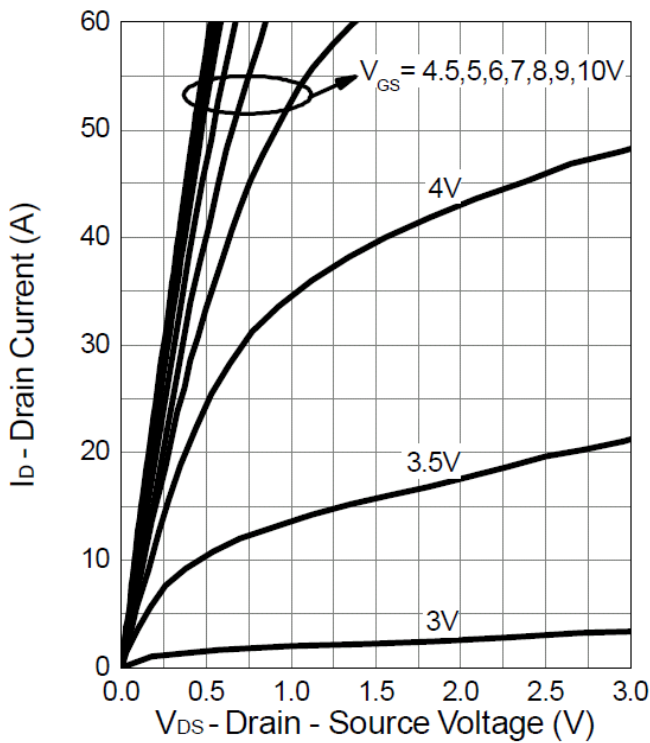
Safe Operation Area



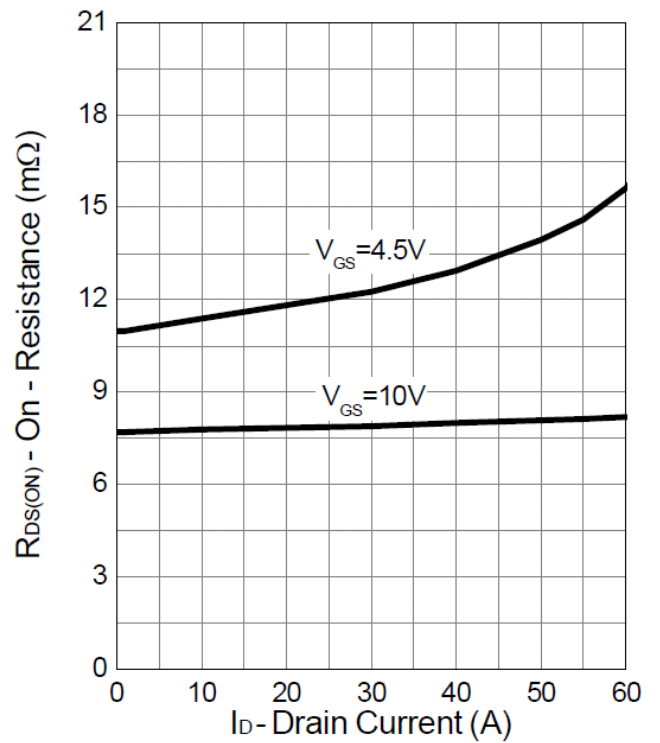
Thermal Transient Impedance



Output Characteristics



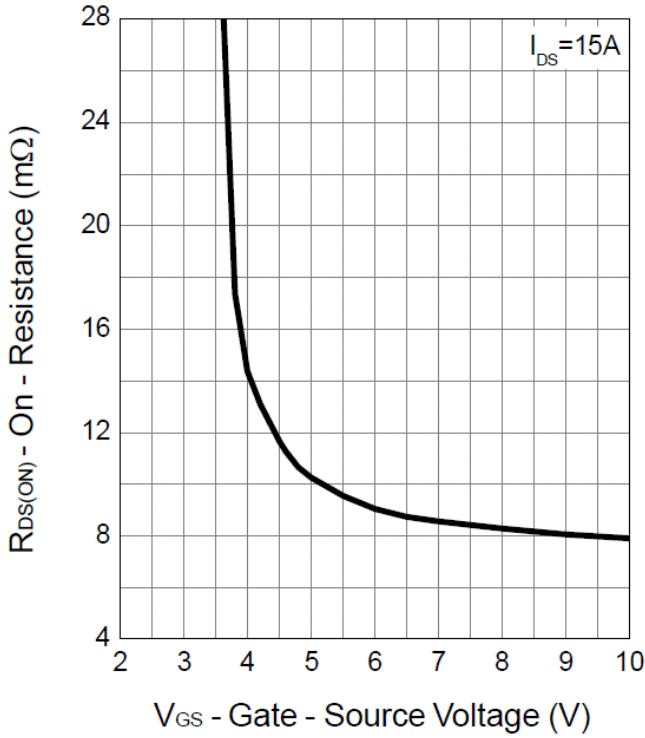
Drain-Source On Resistance



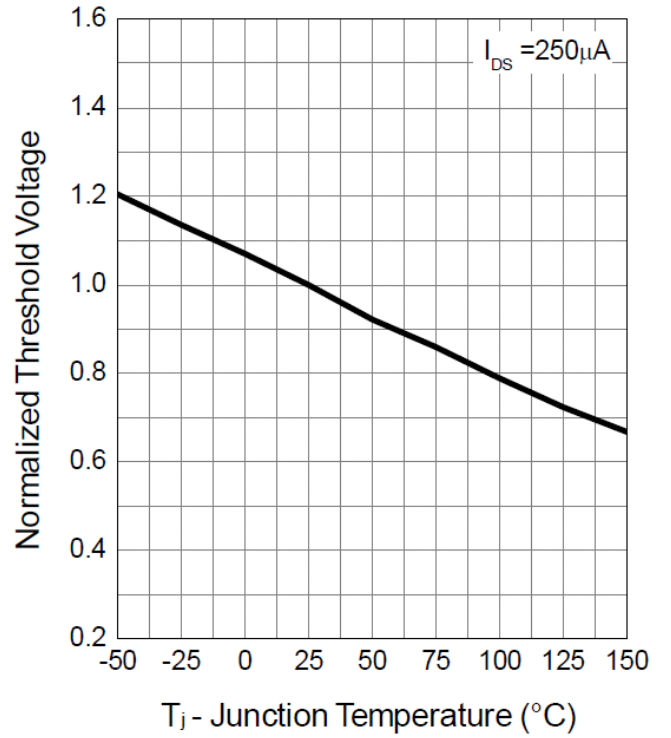
N-Channel Enhancement Mode MOSFET TDM3482

Typical Operating Characteristics(Cont.)

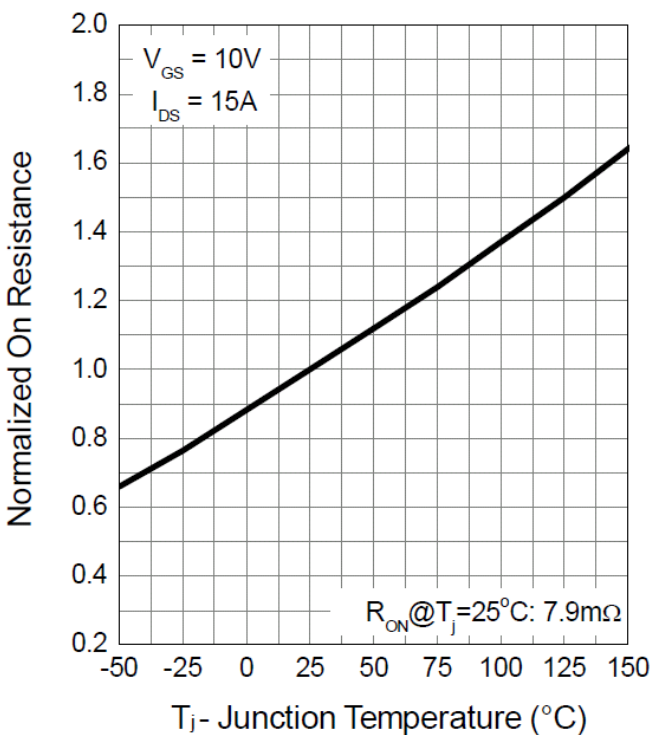
Gate-Source On Resistance



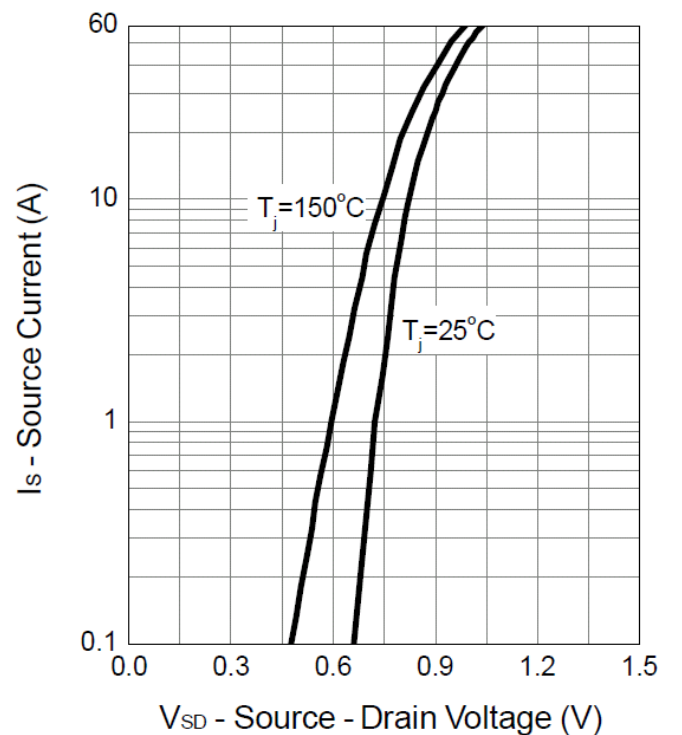
Gate Threshold Voltage



Drain-Source On Resistance

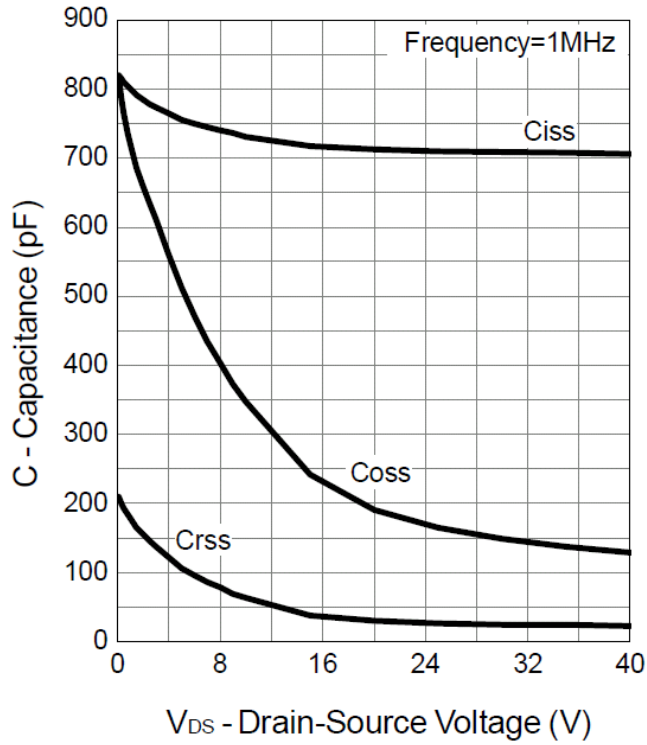


Source-Drain Diode Forward

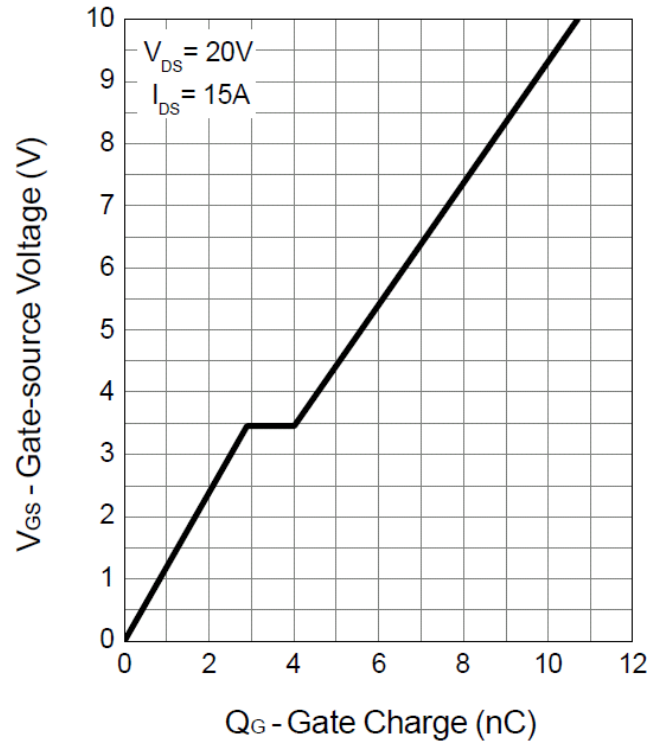


Typical Operating Characteristics(Cont.)

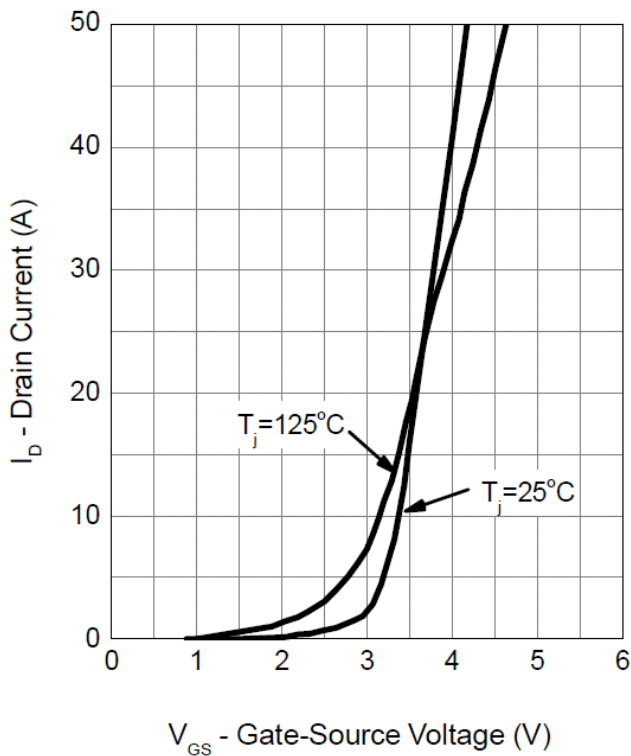
Capacitance



Gate Charge

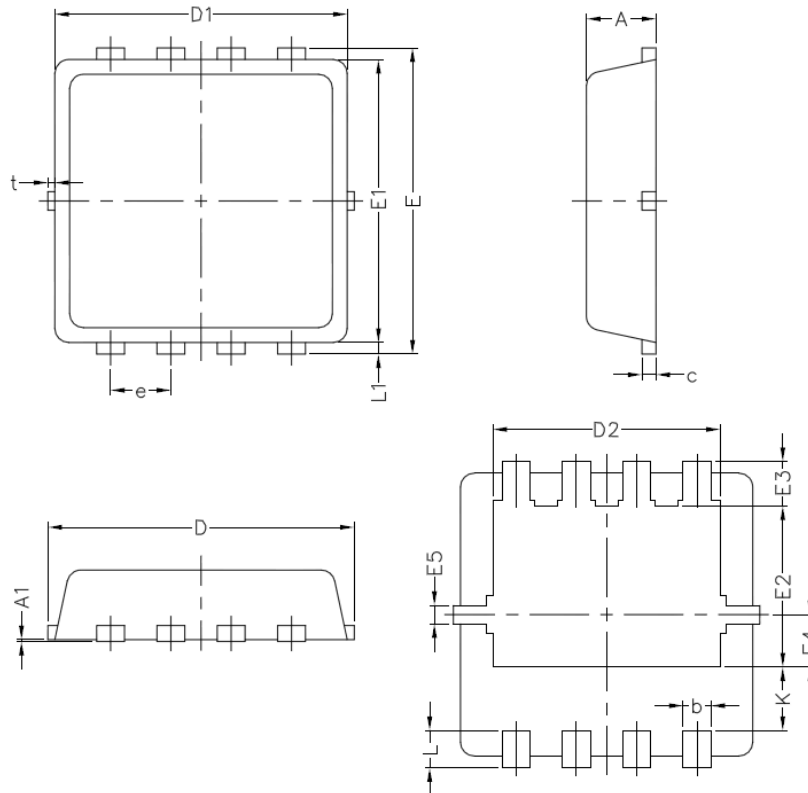


Transfer Characteristics



Package Information

PPAK-3*3-8 Package



Symbol	PPAK-3*3-8(mm)		
	Min	Nom	Max
A	0.70	0.75	0.85
A1	/	/	0.05
b	0.20	0.30	0.40
c	0.10	0.152	0.25
D	3.15	3.3	3.45
D1	3.00	3.15	3.30
D2	2.25	2.45	2.65
E	3.15	3.30	3.45
E1	2.90	3.05	3.20
E2	1.54	1.74	1.94
E3	0.28	0.48	0.68
E4	0.37	0.57	0.77
E5	0.10	0.20	0.30
e	0.60	0.65	0.70
K	0.49	0.69	0.89
L	0.30	0.40	0.50
L1	0.06	0.125	0.20
t	/	/	0.13

Design Notes